

# SOT564-1

plastic thermal enhanced bottom chip carrier; 24 terminals;  
body 4 x 4 x 0.65 mm

20 June 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HBCC24
<b>Package type industry code</b>	HBCC24
<b>Package style descriptive code</b>	HBCC (thermal enhanced bottom chip carrier)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-217
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	12-3-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	3.9	-	4	4.1	mm
A	seated height	-	-	0.8	0.8	mm
A <sub>2</sub>	package height	0.6	-	0.65	0.7	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	24	-	



## 2. Package outline

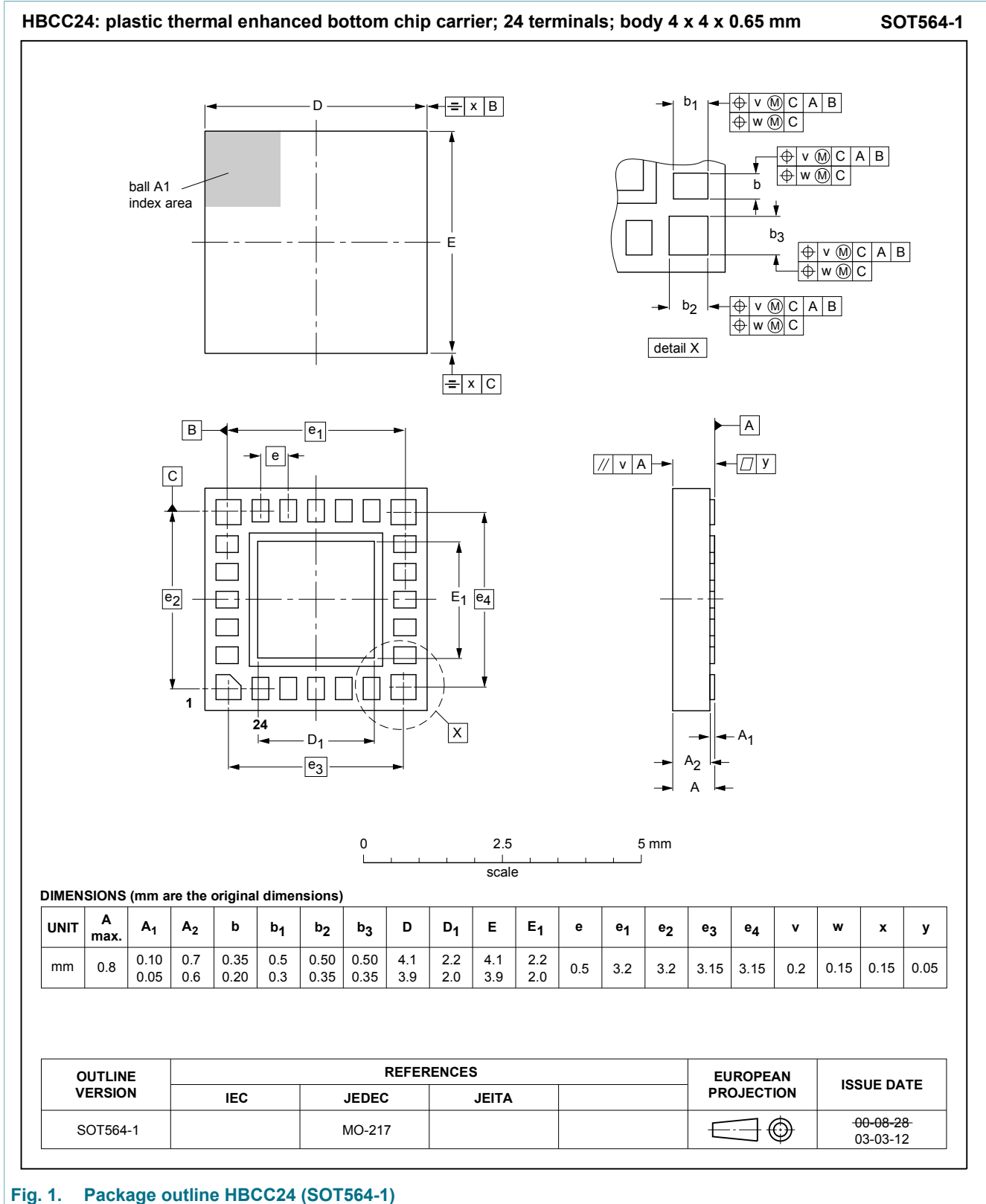


Fig. 1. Package outline HBCC24 (SOT564-1)

### 3. Soldering

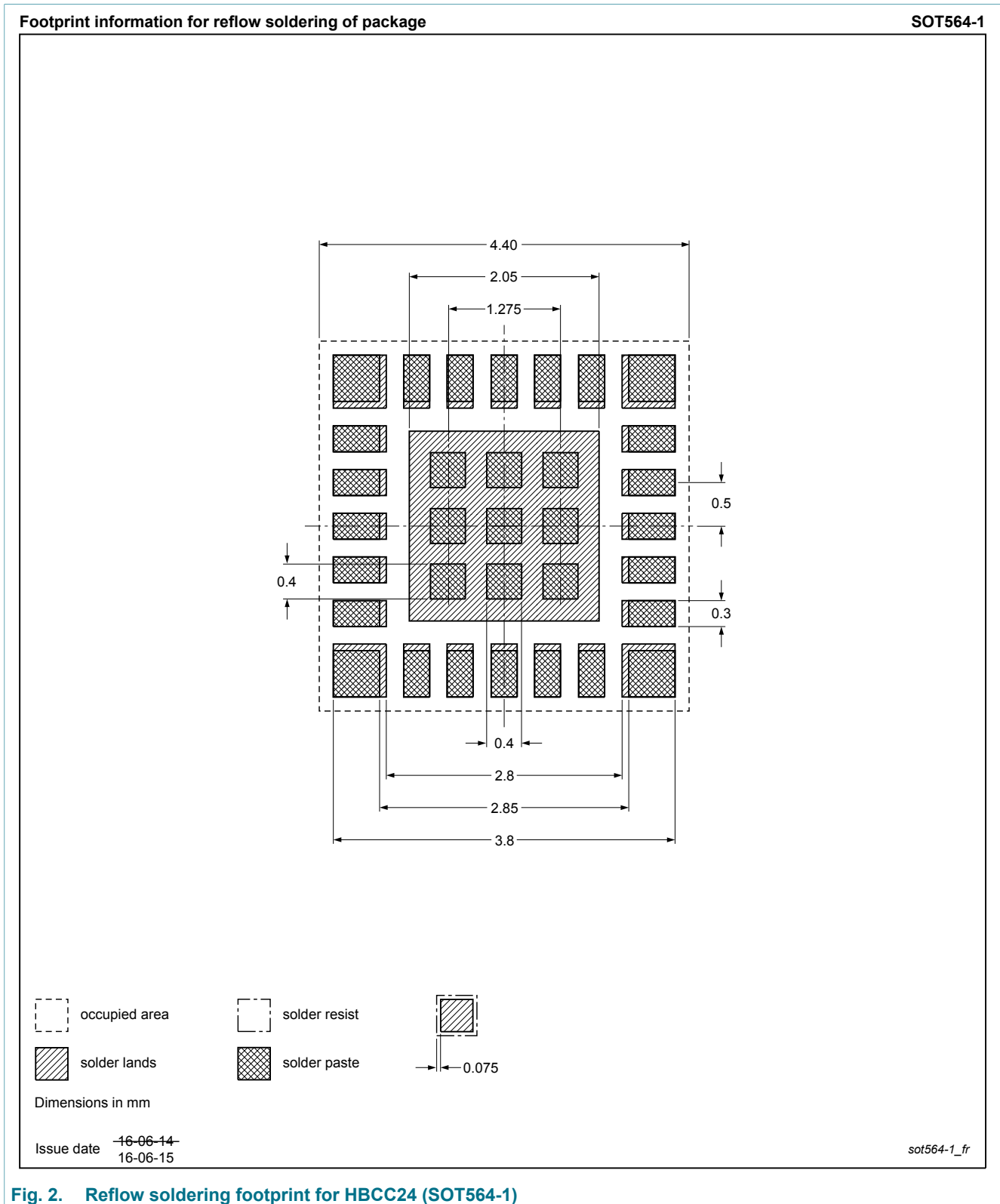


Fig. 2. Reflow soldering footprint for HBCC24 (SOT564-1)

## 4. Legal information

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Date of release: 20 June 2016

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